

CD74ACT14 Hex Schmitt-Trigger Inverter

1 Features

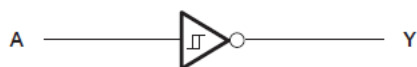
- Inputs are TTL-voltage compatible
- Speed of bipolar F, AS, and S, with significantly reduced power consumption
- Greater noise immunity than standard inverters
- Operates with much slower than standard input rise and fall slew rates
- ± 24 -ma output drive current
 - Fanout to 15 F devices
- SCR-latchup-resistant CMOS process and circuit design

2 Description

The CD74ACT14 contains six independent inverters. This device performs the Boolean function $Y = \bar{A}$.

Package Information

PART NUMBER	PACKAGE ¹	PACKAGE SIZE ²
CD74ACT14	D (SOIC, 14)	8.65 mm x 6 mm
	N (PDIP, 14)	19.3 mm x 9.4 mm



Logic Diagram (Positive Logic)



Table of Contents

1 Features	1	7 Detailed Description	7
2 Description	1	7.1 Overview.....	7
3 Revision History	2	7.2 Functional Block Diagram.....	7
4 Pin Configuration and Functions	3	7.3 Device Functional Modes.....	7
5 Specifications	4	8 Device and Documentation Support	8
5.1 Absolute Maximum Ratings.....	4	8.1 Documentation Support (Analog).....	8
5.2 ESD Ratings.....	4	8.2 Receiving Notification of Documentation Updates.....	8
5.3 Recommended Operating Conditions.....	4	8.3 Support Resources.....	8
5.4 Thermal Information.....	4	8.4 Trademarks.....	8
5.5 Electrical Characteristics.....	4	8.5 Electrostatic Discharge Caution.....	8
5.6 Switching Characteristics.....	5	8.6 Glossary.....	8
5.7 Operating Characteristics.....	5	9 Mechanical, Packaging, and Orderable Information	9
6 Parameter Measurement Information	6		

3 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision A (November 2004) to Revision B (August 2023)	Page
• Added <i>Package Information</i> table, <i>Pin Functions</i> table, <i>ESD Ratings</i> table, <i>Thermal Information</i> table, <i>Device Functional Modes</i> , <i>Device and Documentation Support</i> section, and <i>Mechanical, Packaging, and Orderable Information</i> section	1

4 Pin Configuration and Functions

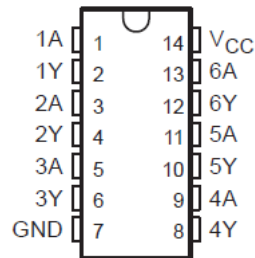


Figure 4-1. CD74AC04 E or M Package (Top View)

Table 4-1. Pin Functions

PIN		I/O	DESCRIPTION
NAME	NO.		
1A	1	Input	Channel 1, Input A
1Y	2	Output	Channel 1, Output Y
2A	3	Input	Channel 2, Input A
2Y	4	Output	Channel 2, Output Y
3A	5	Input	Channel 3, Input A
3Y	6	Output	Channel 3, Output Y
GND	7	—	Ground
4Y	8	Output	Channel 4, Output Y
4A	9	Input	Channel 4, Input A
5Y	10	Output	Channel 5, Output Y
5A	11	Input	Channel 5, Input A
6Y	12	Output	Channel 6, Output Y
6A	13	Input	Channel 6, Input A
V _{CC}	14	—	Positive Supply

5 Specifications

5.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
V_{CC}	Supply voltage	-0.5	6	V
I_{IK}^1	Input clamp current ($V_I < 0$ or $V_I > V_{CC}$)		±20	mA
I_{OK}^1	Output clamp current ($V_O < 0$ or $V_O > V_{CC}$)		±50	mA
I_O	Continuous output current ($V_O = 0$ to V_{CC})		±50	mA
	Continuous current through V_{CC} or GND		±100	mA
T_{stg}	Storage temperature	-65	150	°C

5.2 ESD Ratings

		VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge Human body model (HBM), per ANSI/ESDA/JEDEC JS-001, all pins ⁽¹⁾	±2000	V

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

5.3 Recommended Operating Conditions

		TA = 25°C		- 55°C to 125°C		- 40°C to 85°C		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage	4.5	5.5	4.5	5.5	4.5	5.5	V
V_I	Input voltage	0	V_{CC}	0	V_{CC}	0	V_{CC}	V
V_O	Output voltage	0	V_{CC}	0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current		-24		-24		-24	mA
I_{OL}	Low-level output current		24		24		24	mA
$T_{\Delta t/\Delta v}$	Input transition rise or fall rate		20		20		20	°C

5.4 Thermal Information

THERMAL METRIC ⁽¹⁾		CD74ACT14		UNIT
		E	M	
		14 PINS	14 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	80	86	°C/W

(1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.

5.5 Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	TA = 25°C		- 55°C TO 125°C		- 40°C TO 85°C		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
V_{T+} Positive-going threshold		5 V	1.4	2	1.4	2	1.4	2	V
V_{T-} Negative-going threshold		5 V	0.8	1.3	0.8	1.3	0.8	1.3	V
ΔV_T Hysteresis ($V_{T+} - V_{T-}$)		5 V	0.4		0.4		0.4		V

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	T _A = 25°C		– 55°C TO 125°C		– 40°C TO 85°C		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
V _{OH}	V _I = V _{T+}	I _{OH} = –50 μA	4.5 V	4.4		4.4		4.4	V
		I _{OH} = –24 mA	4.5 V	3.94		3.7		3.8	
		I _{OH} = –50 mA ⁽¹⁾	5.5 V			3.85			
		I _{OH} = –75 mA ⁽¹⁾	5.5 V					3.85	
V _{OL}	V _I = V _{T–}	I _{OL} = 50 μA ⁽¹⁾	4.5 V		0.1		0.1	0.1	V
		I _{OL} = 24 mA ⁽¹⁾	4.5 V		0.36		0.5	0.44	
		I _{OL} = 50 mA ⁽¹⁾	5.5 V				1.65		
		I _{OL} = 75 mA ⁽¹⁾	5.5 V					1.65	
I _I	V _I = V _{CC} or GND	5.5 V		±0.1		±1		±1	μA
I _{CC}	V _I = V _{CC} or GND, I _O = 0	5.5 V		4		80		40	μA
ΔI _{CC} ⁽²⁾	V _I = V _{CC} – 2.1 V	4.5 V to 5.5 V		2.4		3		2.8	mA
C _i				10		10		10	pF

- (1) Test one output at a time, not exceeding 1-second duration. Measurement is made by forcing indicated current and measuring voltage to minimize power dissipation. Test verifies a minimum 50-Ω transmission-line drive capability at 85°C and 75-Ω transmission-line drive capability at 125°C.
- (2) Additional quiescent supply current per input pin, TTL inputs high, 1 unit load.

Table 5-1. Act Input Load Table

INPUT	UNIT LOAD
A	0.21

1. Unit load is ΔI_{CC} limit specified in electrical characteristics table (e.g., 2.4 mA at 25°C).

5.6 Switching Characteristics

over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see [Load Circuit and Voltage Waveforms](#))

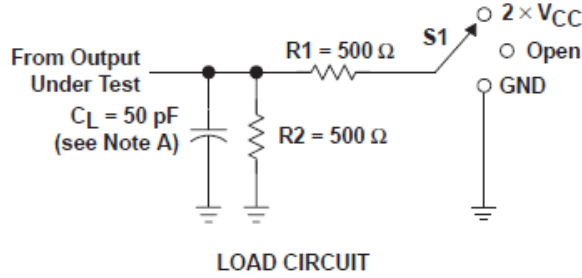
PARAMETER	FROM (INPUT)	TO (OUTPUT)	– 55°C to 125°C		– 40°C to 85°C		UNIT
			MIN	MAX	MIN	MAX	
t _{PLH}	A	Y	3.6	14.5	3.7	13.2	ns
t _{PHL}			2.4	9.5	2.4	8.6	

5.7 Operating Characteristics

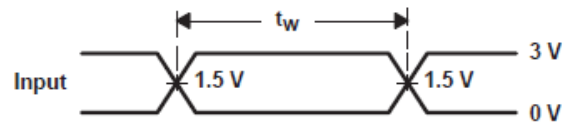
V_{CC} = 5 V, T_A = 25°C

PARAMETER		TYP	UNIT
C _{pd}	Power dissipation capacitance	45	pF

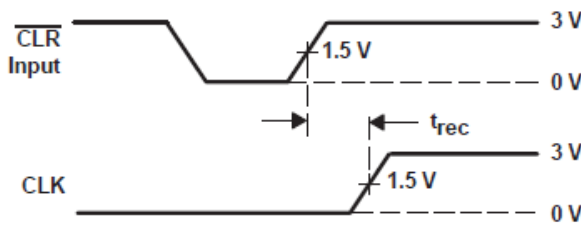
6 Parameter Measurement Information



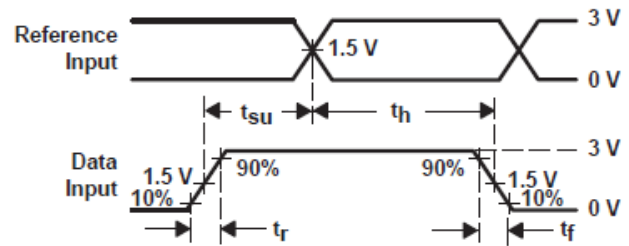
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	$2 \times V_{CC}$
t_{PHZ}/t_{PZH}	GND



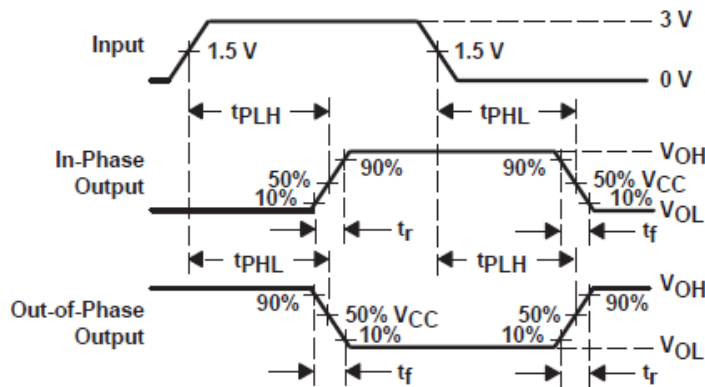
VOLTAGE WAVEFORMS
PULSE DURATION



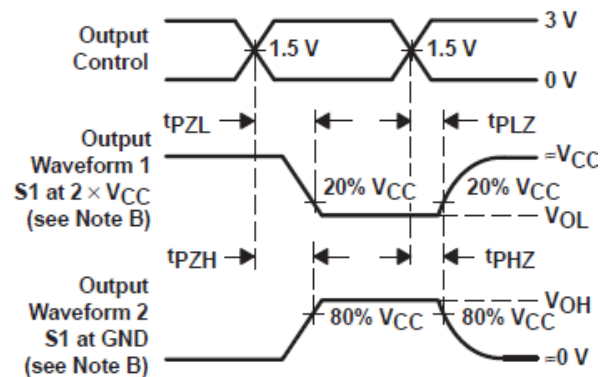
VOLTAGE WAVEFORMS
RECOVERY TIME



VOLTAGE WAVEFORMS
SETUP AND HOLD AND INPUT RISE AND FALL TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY AND OUTPUT TRANSITION TIMES



VOLTAGE WAVEFORMS
OUTPUT ENABLE AND DISABLE TIMES

- NOTES: A. C_L includes probe and test-fixture capacitance.
- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r = 3 \text{ ns}$, $t_f = 3 \text{ ns}$. Phase relationships between waveforms are arbitrary.
- D. For clock inputs, f_{max} is measured with the input duty cycle at 50%.
- E. The outputs are measured one at a time, with one input transition per measurement.
- F. t_{PLH} and t_{PHL} are the same as t_{pd} .
- G. t_{pZL} and t_{pZH} are the same as t_{en} .
- H. t_{pLZ} and t_{pHZ} are the same as t_{dis} .

Figure 6-1. Load Circuit and Voltage Waveforms

7 Detailed Description

7.1 Overview

The CD74ACT14 contains six independent inverters. This device performs the Boolean function $Y = \bar{A}$.

Each circuit functions as an independent inverter, but because of the Schmitt action, the inverters have different input threshold levels for positive-going (V_{T+}) and negative-going (V_{T-}) signals.

7.2 Functional Block Diagram



Figure 7-1. Logic Diagram, Each Inverter (Positive Logic)

7.3 Device Functional Modes

Table 7-1. Function Table (Each Inverter)

INPUT	OUTPUT
A	Y
H	L
L	H

8 Device and Documentation Support

8.1 Documentation Support (Analog)

8.1.1 Related Documentation

The table below lists quick access links. Categories include technical documents, support and community resources, tools and software, and quick access to sample or buy.

Table 8-1. Related Links

PARTS	PRODUCT FOLDER	SAMPLE & BUY	TECHNICAL DOCUMENTS	TOOLS & SOFTWARE	SUPPORT & COMMUNITY
CD74ACT14	Click here	Click here	Click here	Click here	Click here

8.2 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. Click on *Subscribe to updates* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

8.3 Support Resources

[TI E2E™ support forums](#) are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

Linked content is provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

8.4 Trademarks

TI E2E™ is a trademark of Texas Instruments.

All trademarks are the property of their respective owners.

8.5 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

8.6 Glossary

[TI Glossary](#) This glossary lists and explains terms, acronyms, and definitions.

9 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
CD74ACT14E	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-55 to 125	CD74ACT14E	Samples
CD74ACT14M96	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	ACT14M	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

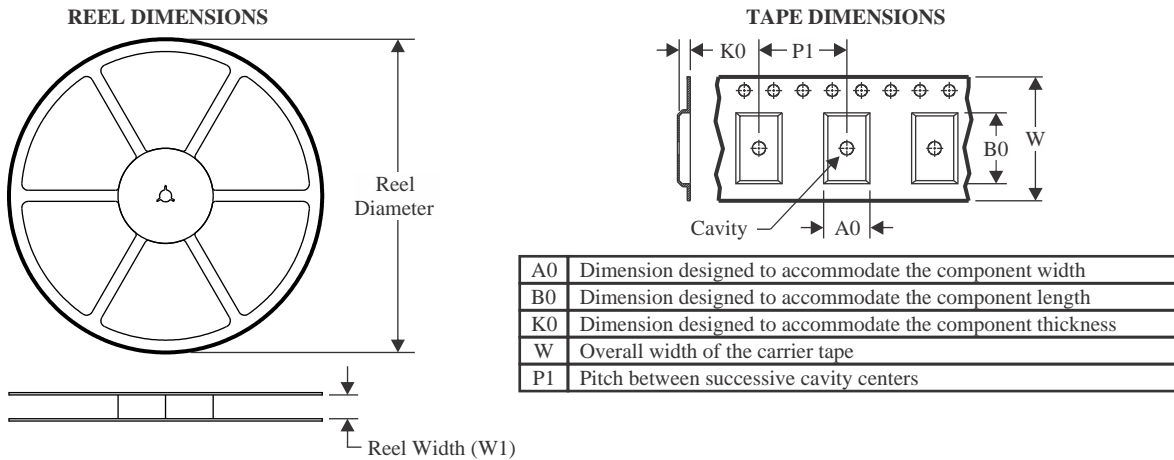
(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer:The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

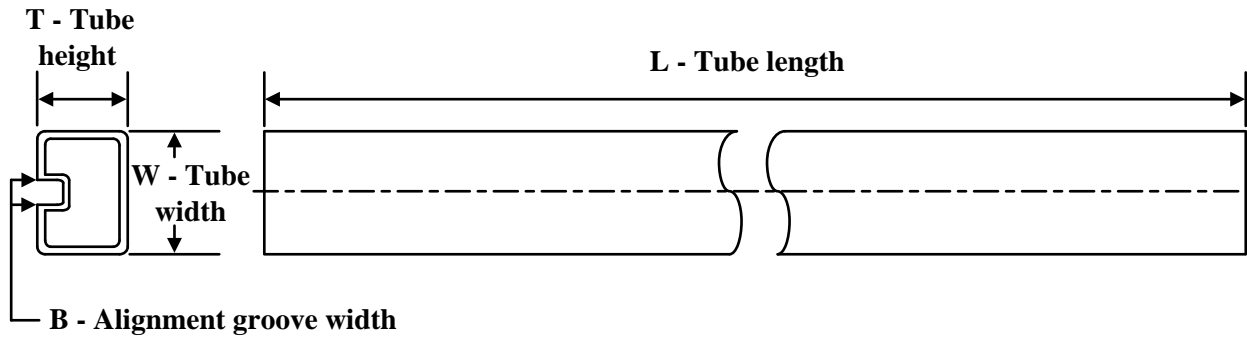

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD74ACT14M96	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD74ACT14M96	SOIC	D	14	2500	356.0	356.0	35.0

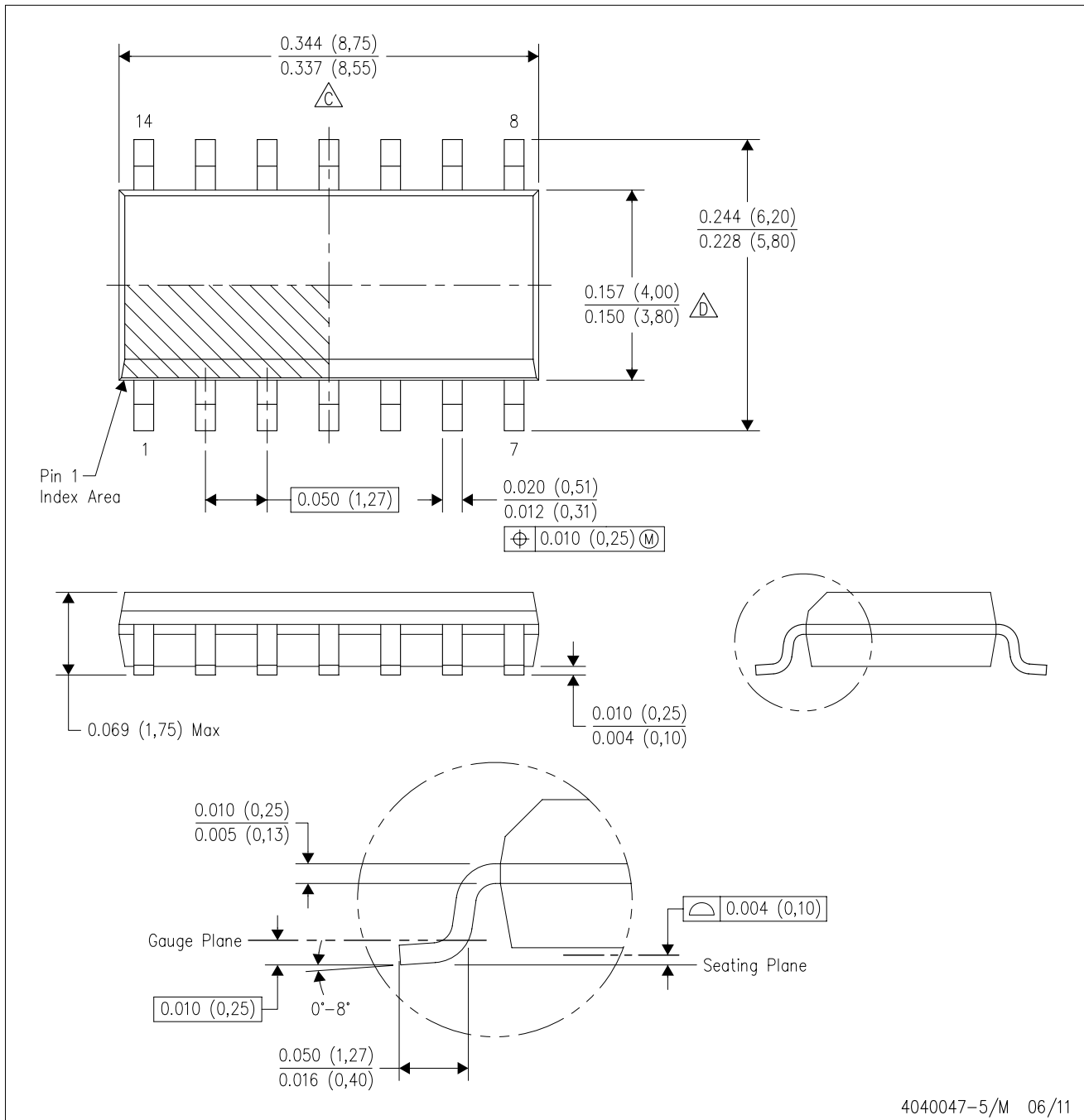
TUBE




*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
CD74ACT14E	N	PDIP	14	25	506	13.97	11230	4.32
CD74ACT14E	N	PDIP	14	25	506	13.97	11230	4.32

D (R-PDSO-G14)

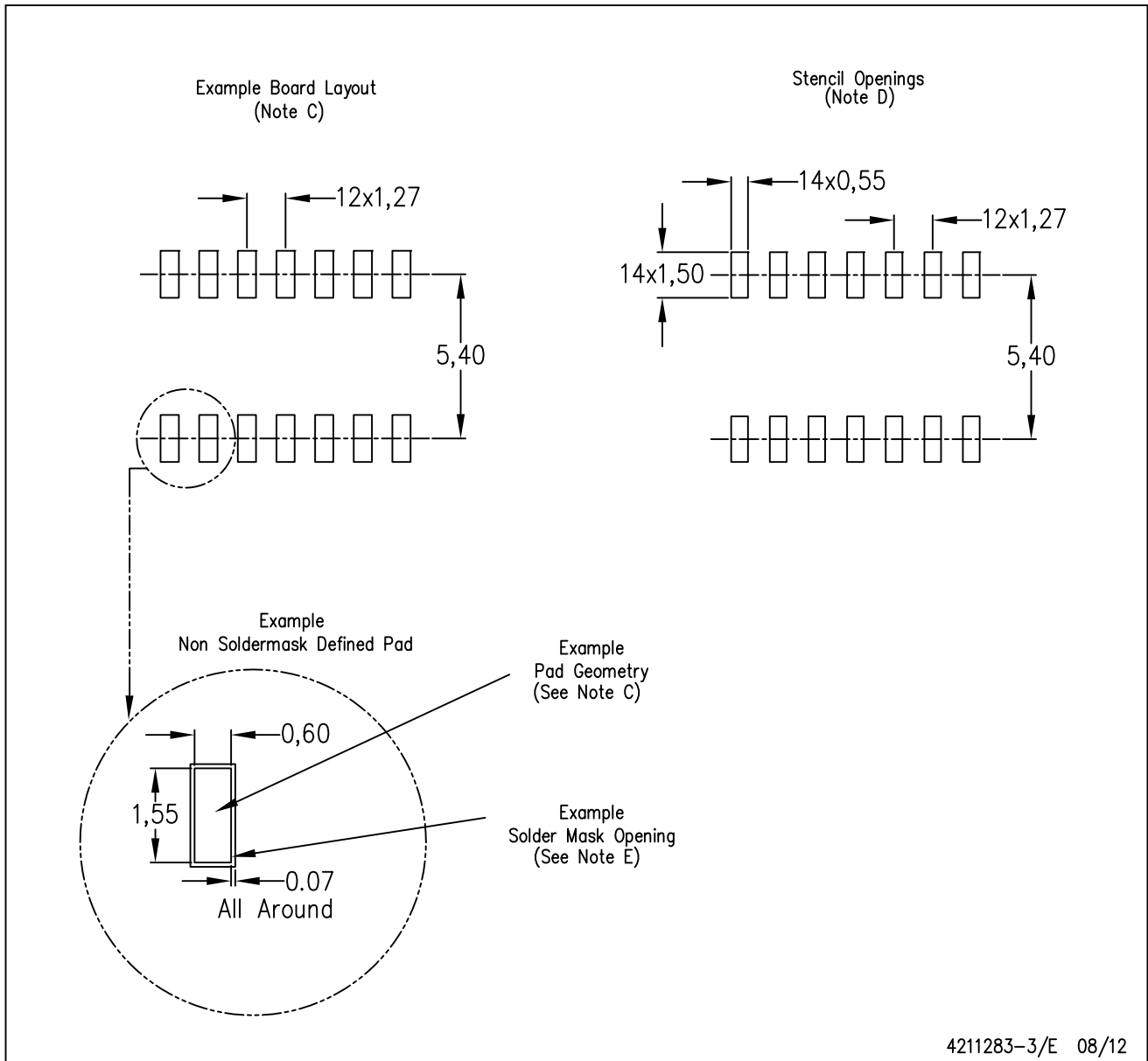
PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 -  Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 -  Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AB.

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - $\triangle C$ Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - $\triangle D$ The 20 pin end lead shoulder width is a vendor option, either half or full width.

4040049/E 12/2002

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATA SHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to [TI's Terms of Sale](#) or other applicable terms available either on [ti.com](https://www.ti.com) or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

TI objects to and rejects any additional or different terms you may have proposed.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2023, Texas Instruments Incorporated